

- NOTES:**
- All voltages are measured with a VTVM (11 mega-ohms/V) from a p.c. board ground and with the transceiver connected to an external power supply adjusted for 13.8 VDC. All readings are measured with the transceiver in the receive mode with no signal and squelched (except as noted). All are in VDC (except as noted). If measurements obtained exceed $\pm 20\%$ of the indicated values, the cause of the difference should be corrected.
 - All resistors $\frac{1}{4}$ watt, 5%, except as noted. All capacitors in μF , except as noted.
 - Symbols used —
 - \square — receive voltage, squelched
 - Δ — transmit voltage, unmodulated
 - Δ_M — transmit voltage, modulated (whistle)
 - \circ — factory selected value
 - $*$ — field-selectable component and/or value
 - \perp — chassis ground
 - $\text{---}\perp$ — p.c. board ground
 - \diamond — component mounted on foil side of p.c. board
 - $\text{---}\square$ — unshielded, constructed component
 - $\text{---}\square$ — shielded component

| | | | |
|---------|-----------|---------|-----------|
| X Tol 1 | 23.290MHz | X Tol 7 | 14.950MHz |
| 2 | 23.340 | 8 | 14.960 |
| 3 | 23.390 | 9 | 14.970 |
| 4 | 23.440 | 10 | 14.990 |
| 5 | 23.490 | 11 | 11.275 |
| 6 | 23.540 | 12 | 11.730 |

SEMICONDUCTOR TERMINAL CONNECTION (BOTTOM VIEW UNLESS OTHERWISE NOTED)

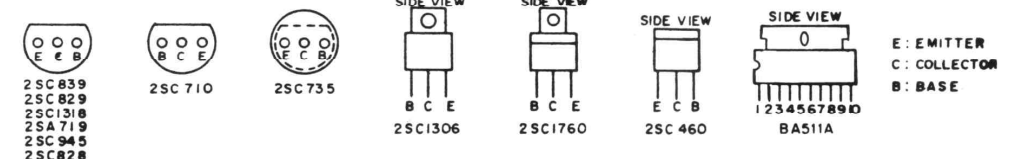


Figure 4-9. Schematic Diagram, 670B, Stage 2

1975 - 4 - 16
4 - 25
5 - 26